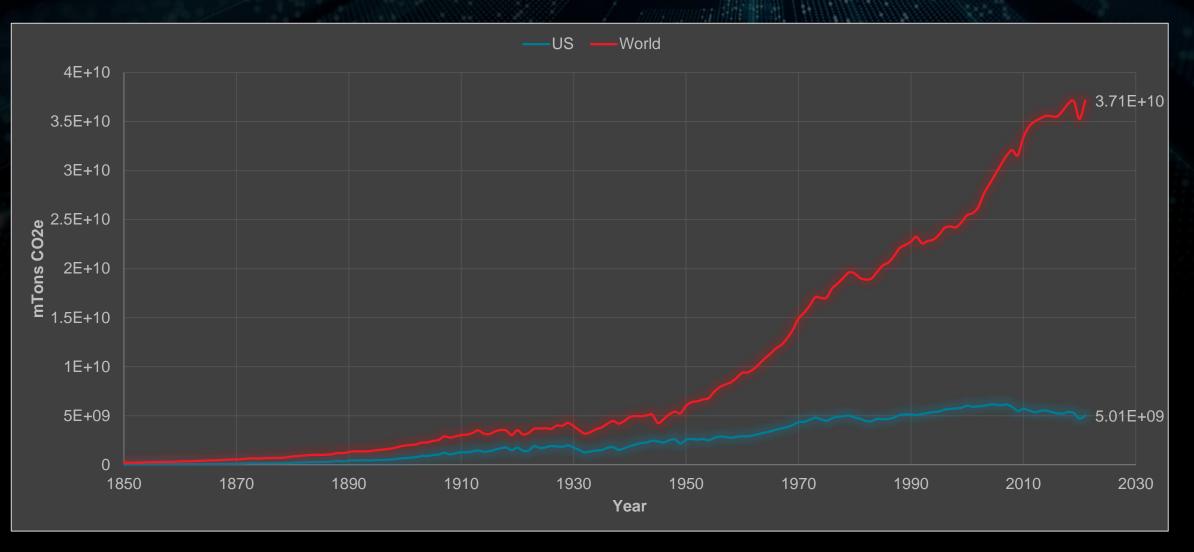
Sustainable Computing at Scale

Srilatha (Bobbie) Manne Senior Fellow, AMD



Compute Carbon Emissions

Carbon Emissions Over Time



Hannah Ritchie, Max Roser and Pablo Rosado (2020) - "CO₂ and Greenhouse Gas Emissions". Published online at OurWorldInData.org. Retrieved from: 'https://ourworldindata.org/co2-and-greenhouse-gas-emissions' [Online Resource] AMD together we advance_

Empire State Building: 331,122 metric tons

>10,000 Empire State Buildings worth of carbon per year

Data Center Power Use

- Up to 460 TWh of electricity/year in 2022⁺
- 2% of global energy demand⁺

Equivalent to 1 year of *



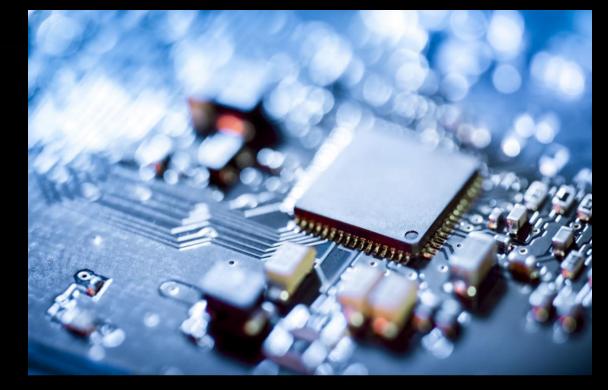
⁺IEA (2024), Electricity 2024, IEA, Paris https://www.iea.org/reports/electricity-2024, Licence: CC BY 4.0

* Based on EPA Greenhouse Gas Equivalences Calculator calculated on 3/20/2024

Hardware Innovations Over Last 5 Decades



>2000 times faster

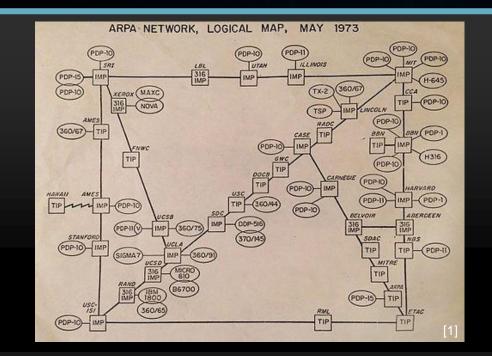


>3000 times smaller

Analysis based on comparing an AMD AM9080 processor running at 2MHz to an AMD Ryzen 9 7950X with base clock frequency of 4.5GHz.



The Past 50 Years



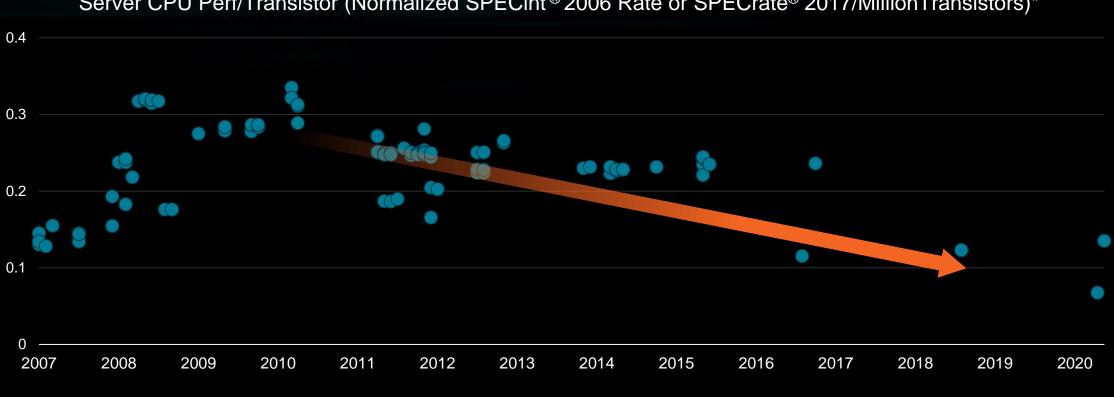


1973 ARPANET: 42 computers

2023: Over 42 Billion connected devices^[2]



Transistors and Performance



Server CPU Perf/Transistor (Normalized SPECint® 2006 Rate or SPECrate® 2017/MillionTransistors)*

Another way to look at this is through the lens of performance/transistor

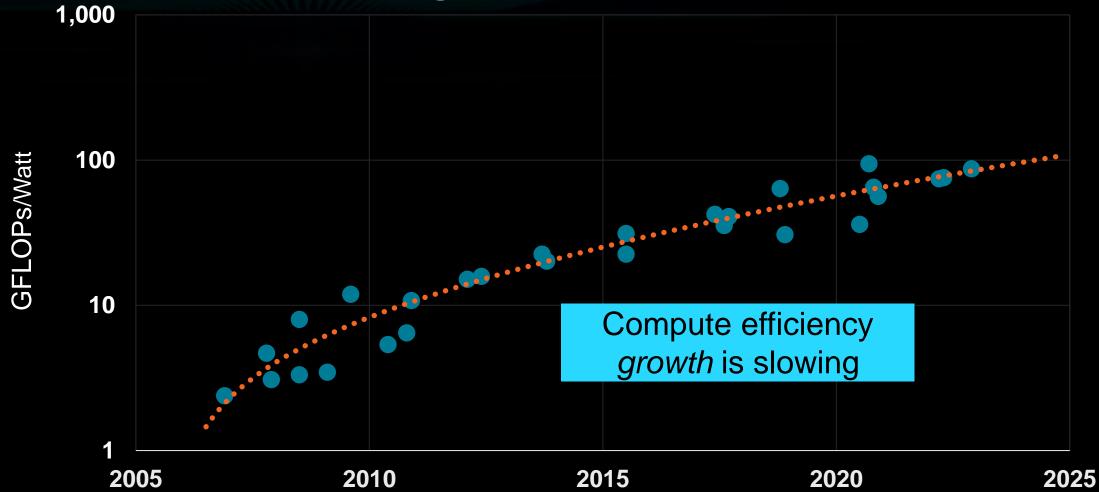
We're using more of them to extract a unit of performance

*Normalized SPECint[®] 2006 Rate and SPECrate[®] 2017 published results from <u>www.spec.org</u> as of 12/31/20 divided by total CPU transistors. SPEC[®], SPEC CPU[®], SPECrate[®], and the benchmark name SPECint[®] are registered trademarks of the Standard Performance Evaluation Corporation (www.spec.org). SPEC CPU[®] 2006 is a retired benchmark and SPEC[®] is no longer reviewing or publishing SPEC[®] CPU 2006 results.

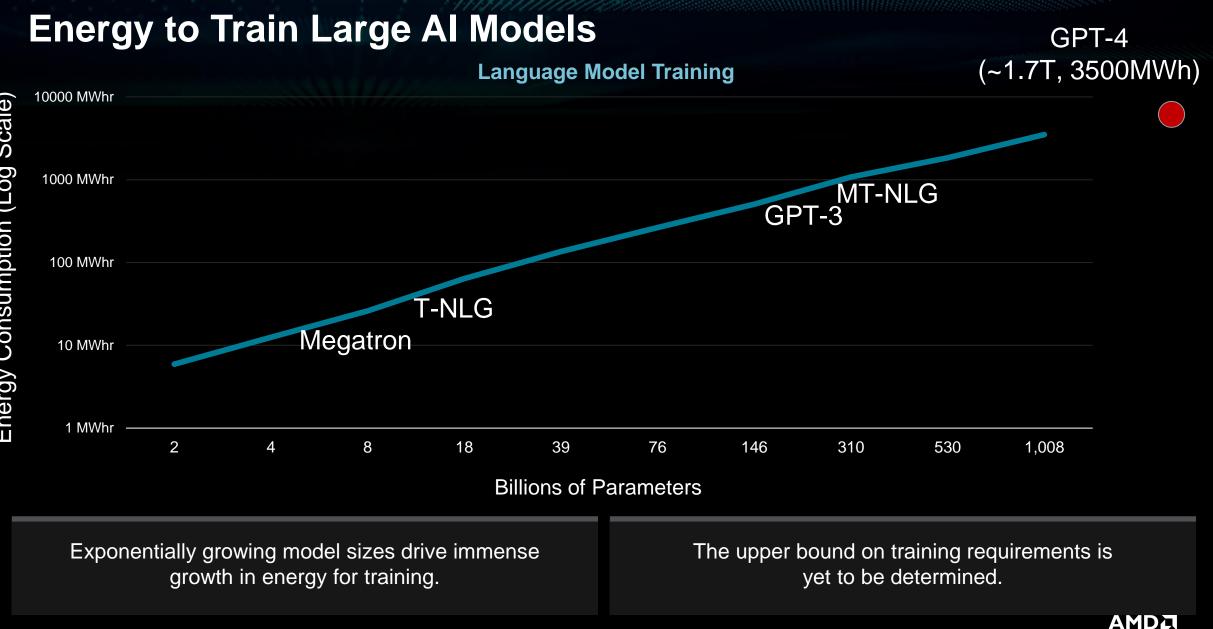


Compute Efficiency Trends

GPU Single Precision FLOPs/Watt



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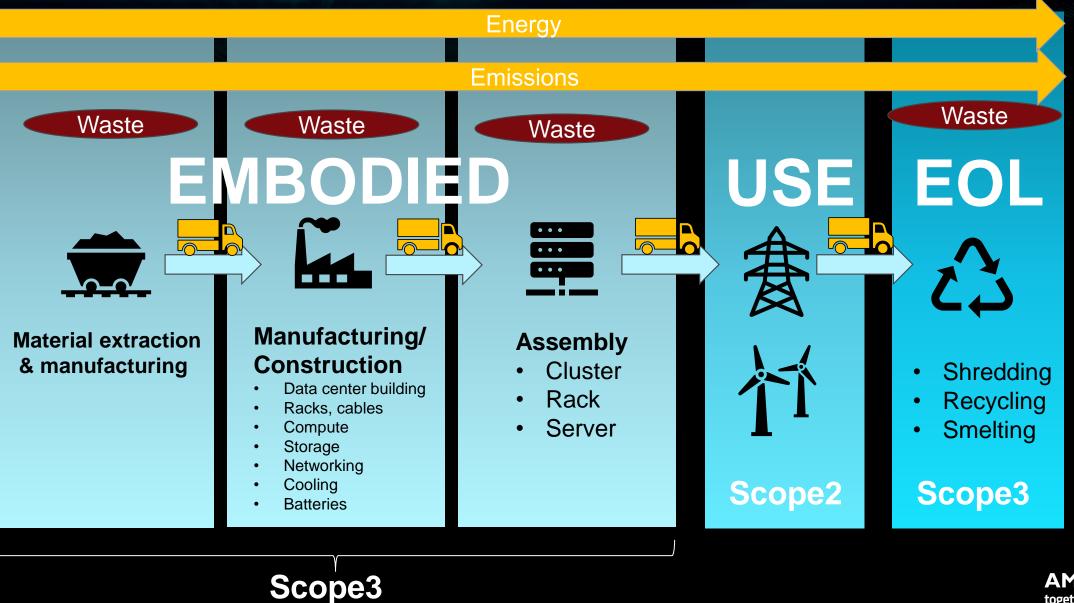
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Carbon Footprint

C

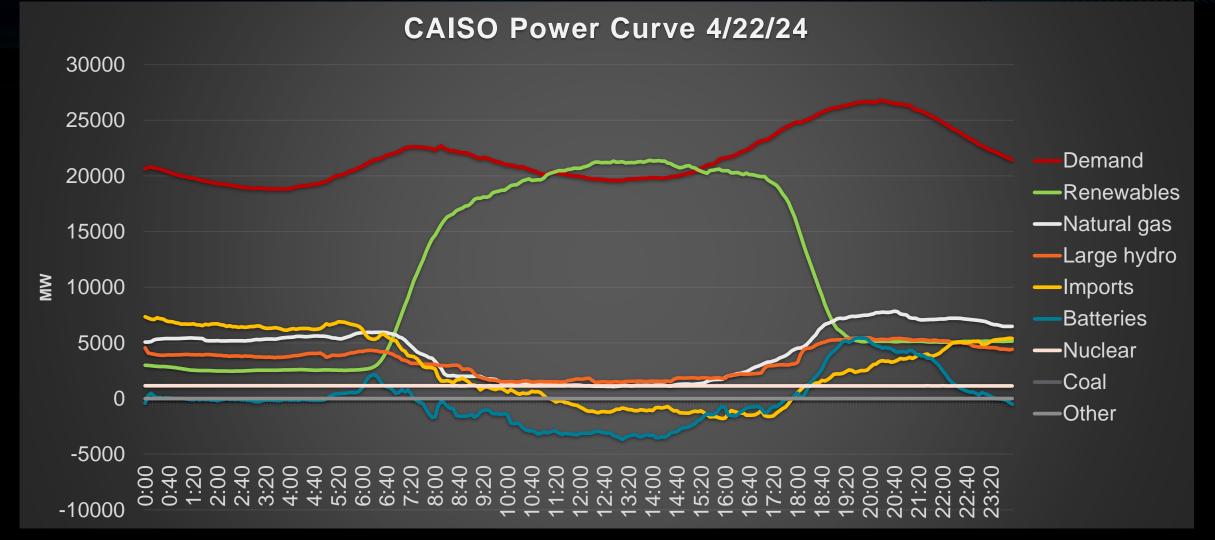
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Data Center Carbon Footprint

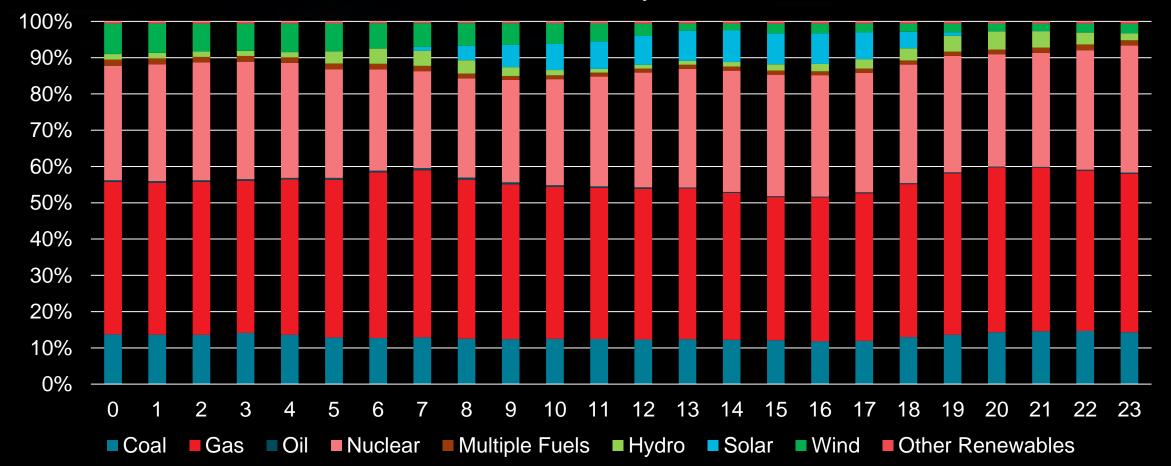


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Renewable Energy in CA



Data from California Independent System Operator



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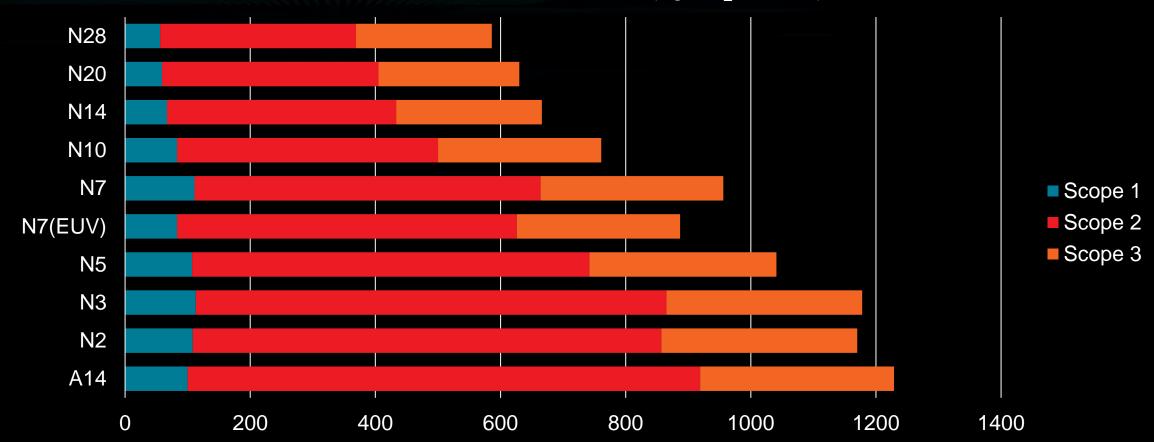
4/22/24: PJM Electricity Generation

Data from PJM generation by fuel type: https://dataminer2.pjm.com/feed/gen_by_fuel

Fuel Mix in PJM Grid

Estimated Silicon Manufacturing Emissions

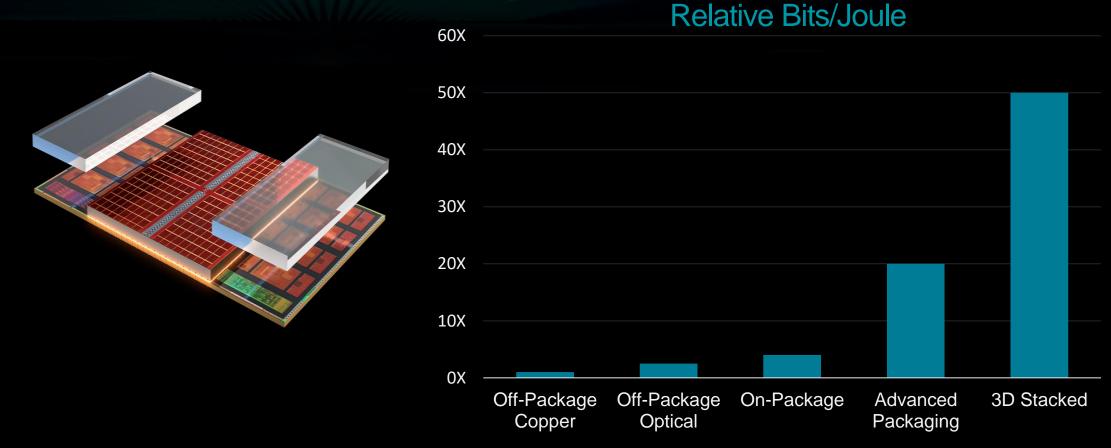
Total Emissions Per Wafer (kgCO₂e/wafer)



Data from "Cradle-to-gate Life Cycle Assessment of CMOS Logic Technologies", L Boakes et al., IEDM 2023

Compute Efficiency Examples

3D Chiplets and Communication Power

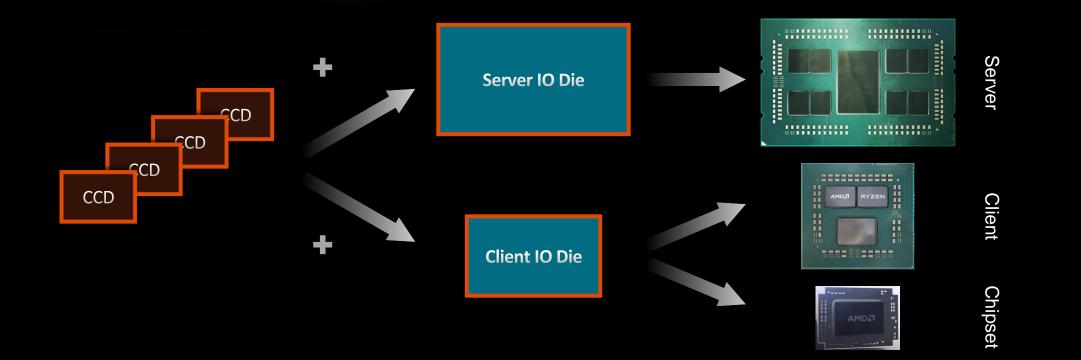


Advanced Packaging Provides up to a 50x Reduction in Communication Power



INTERNAL AMD DATA

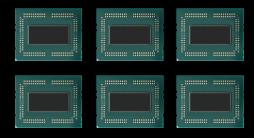
Chiplets and Reuse





Test

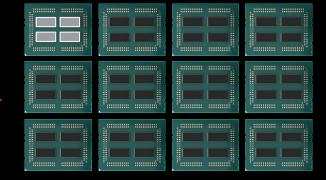
Functional SoCs







Assemble

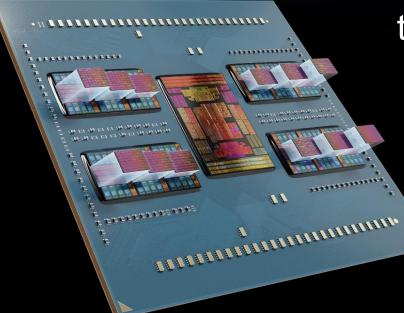


Many More Functional SoCs Ability to mix and match at a finer grained level

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Wafer

EPYC[™] Embodied Carbon Savings with Chiplets



~132,000 metric tons CO2e saved in 2023 through avoidance of wafers manufactured ^[1]

(Up to 12 CCD chiplets versus 1 monolithic die)

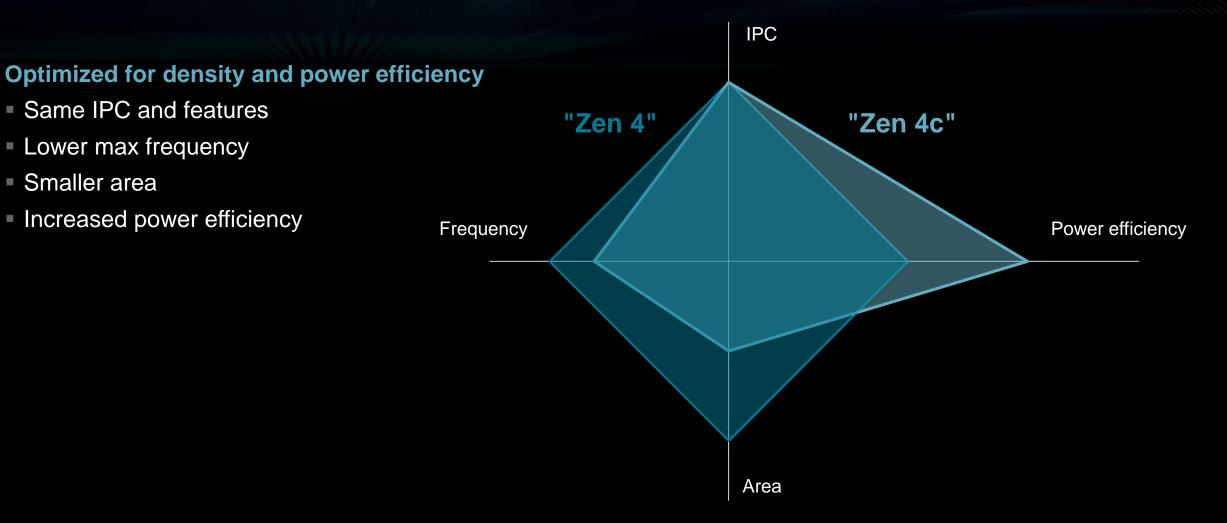
Equivalent to:

- 2.8X the operational CO2e of AMD in 2023
- 14.9 million gallons of gas^[2]
- Yearly electricity for ~26,000 homes^[2]

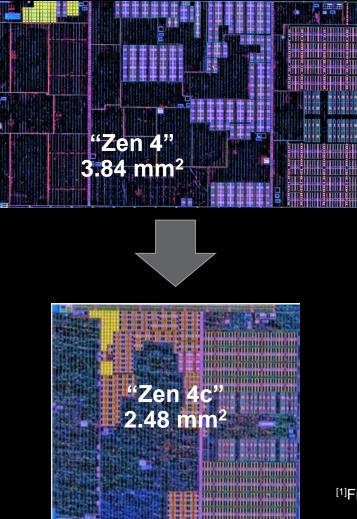
^[1]AMD estimation based on defect density (defects per unit area on the wafer), chip area and n-factor (manufacturing complexity factor) to estimate the number of wafers avoided in one year. Yield = $(1 + A*D0)^{(-n)}$ where A is the chip area, D0 is the defect density and n is the complexity factor. The area is known from our design, D0 is known based our manufacturing yield data, and n is a number provided by a foundry partner for a given technology. The calculations are not meant to be precise, since chip design can have a large influence on yield, but it estimates the area impact on yield. The carbon emission estimates of 132,000 mtCO2e were calculated using the estimated number of 5 nm wafers saved in one year, based on the TechInsights' Semiconductor Manufacturing Carbon Model. Comparison to AMD corporate footprint is based on AMD reported scope 1 and 2 market-based GHG emissions in 2023: 46,605 tCO2e.

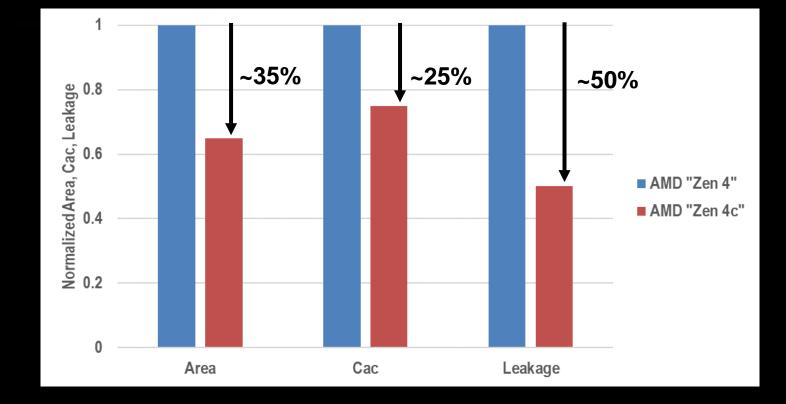
^[2] Data generated from the EPA Greenhouse Gas Equivalency Calculator on 7/31/2024: https://www.epa.gov/energy/greenhouse-gasequivalencies-calculator

"Zen 4c" – a Compact "Zen 4"



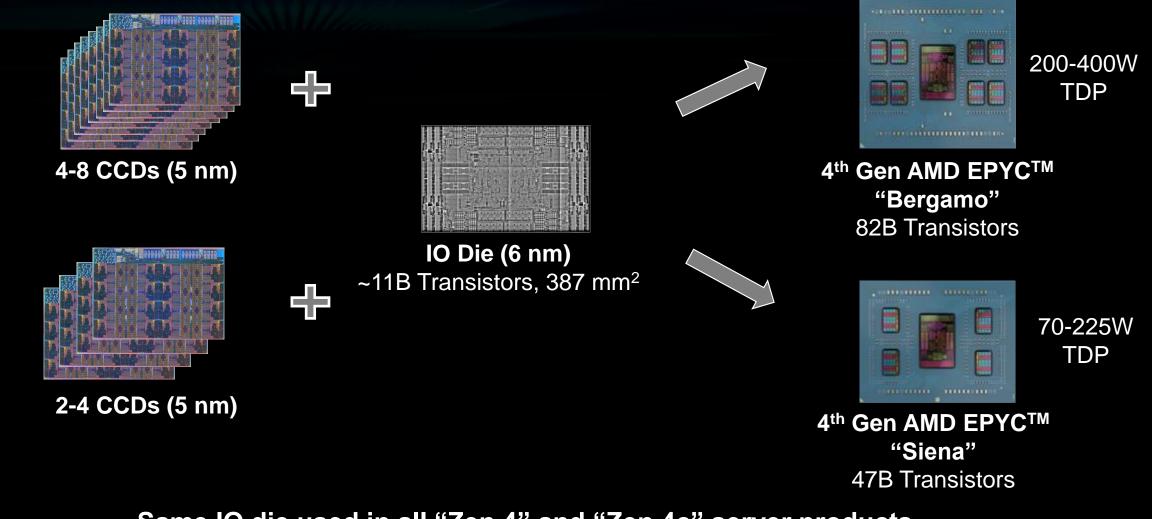
Benefits of Specialization^[1]





^[1]Figures and data from "Zen 4c": The AMD 5nm Area-Optimized x86-64 Microprocessor Core, T. Burd et. Al., ISSCC 2024

Zen4C Server Configurations



Same IO die used in all "Zen 4" and "Zen 4c" server products

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Other Sustainable Solutions

SMT • Increases utilization of wide pipelines	Virtualization • Better utilization of SOC	 Disaggregation Less fragmentation and waste through pooling of resources Reuse of older technology
Reconfigurable Hardware	Component Redundancy	Power Oversubscription
 Multi-purpose use 	 Improves yield and increases lifetime 	 Improves data center capacity

NEW CHALLENGES



The Power Problem: Transmission Issues SlowData Center GrowthData Center Frontier

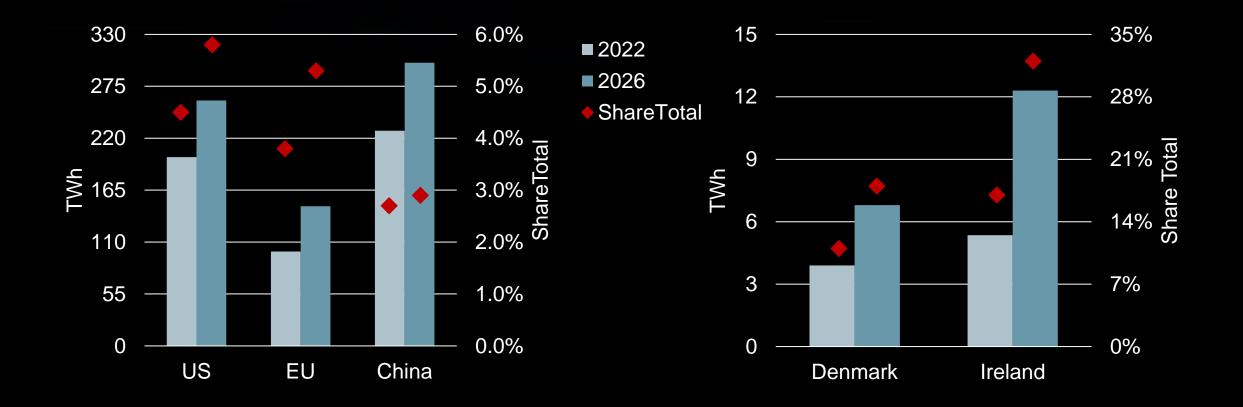
Power Shortages Are Turning More Data Centers Into Their Own Utilities Bisnow

Al Is Changing the Future of Energy. What to Barrons

Amid record high energy demand, America isrunning out of electricityWashington Post

Amazon goes nuclear, acquires atomic datacenter for \$650M The Register

Data Center Demand Projections



Takeaways



DESIGN FOR DISRUPTION

DESIGN FOR ALL



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